

## GI01L60

### N-CHANNEL ENHANCEMENT MODE POWER MOSFET

BVDSS	600V
RDS(ON)	12Ω
ID	1A

### Description

The GI01L60 (through-hole version) is available for low-profile applications and suited for AC/DC converters.

### Features

- \*Repetitive Avalanche Rated
- \*Simple Drive Requirement
- \*Fast Switching Speed
- \*RoHS Compliant

### Package Dimensions

**TO-251**

**Marking :**

REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	6.40	6.80	G	0.50	0.70
B	5.20	5.50	H	2.20	2.40
C	6.80	7.20	J	0.45	0.55
D	7.20	7.80	K	0.45	0.60
E	2.30 REF.		L	0.90	1.50
F	0.60	0.90	M	5.40	5.80

### Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DS}$	600	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Continuous Drain Current, $V_{GS}@10V$	$I_D @T_C=25^\circ C$	1	A
Continuous Drain Current, $V_{GS}@10V$	$I_D @T_C=100^\circ C$	0.8	A
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	3	A
Total Power Dissipation	$P_D @T_C=25^\circ C$	29	W
Linear Derating Factor		0.232	W/ $^\circ C$
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	0.5	mJ
Avalanche Current	$I_{AR}$	1	A
Repetitive Avalanche Energy	$E_{AR}$	0.5	mJ
Operating Junction and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150	$^\circ C$

### Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-case Max.	$R_{thj-case}$	4.3	$^\circ C/W$
Thermal Resistance Junction-ambient Max.	$R_{thj-amb}$	110	$^\circ C/W$

**Electrical Characteristics(T<sub>j</sub> = 25°C Unless otherwise specified)**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	600	-	-	V	V <sub>GS</sub> =0, I <sub>D</sub> =1mA
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS} / \Delta T_j$	-	0.8	-	V/°C	Reference to 25°C, I <sub>D</sub> =1mA
Gate Threshold Voltage	V <sub>GS(th)</sub>	2.0	-	4.0	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA
Forward Transconductance	g <sub>fs</sub>	-	0.8	-	S	V <sub>DS</sub> =10V, I <sub>D</sub> =0.5A
Gate-Source Leakage Current	I <sub>GSS</sub>	-	-	±100	nA	V <sub>GS</sub> = ±30V
Drain-Source Leakage Current(T <sub>j</sub> =25°C)	I <sub>DSS</sub>	-	-	10	uA	V <sub>DS</sub> =600V, V <sub>GS</sub> =0
Drain-Source Leakage Current(T <sub>j</sub> =150°C)		-	-	100	uA	V <sub>DS</sub> =480V, V <sub>GS</sub> =0
Static Drain-Source On-Resistance <sup>3</sup>	R <sub>DS(ON)</sub>	-	-	12	Ω	V <sub>GS</sub> =10V, I <sub>D</sub> =0.5A
Total Gate Charge <sup>3</sup>	Q <sub>g</sub>	-	4.0	-	nC	I <sub>D</sub> =1A V <sub>DS</sub> =480V V <sub>GS</sub> =10V
Gate-Source Charge	Q <sub>gs</sub>	-	1.0	-		
Gate-Drain ("Miller") Change	Q <sub>gd</sub>	-	1.1	-		
Turn-on Delay Time <sup>2</sup>	T <sub>d(on)</sub>	-	6.6	-	ns	V <sub>DD</sub> =300V I <sub>D</sub> =1A V <sub>GS</sub> =10V R <sub>G</sub> =3.3Ω R <sub>D</sub> =300Ω
Rise Time	T <sub>r</sub>	-	5.0	-		
Turn-off Delay Time	T <sub>d(off)</sub>	-	11.7	-		
Fall Time	T <sub>f</sub>	-	9.2	-		
Input Capacitance	C <sub>iss</sub>	-	170	-	pF	V <sub>GS</sub> =0V V <sub>DS</sub> =25V f=1.0MHz
Output Capacitance	C <sub>oss</sub>	-	30.7	-		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	5.1	-		

**Source-Drain Diode**

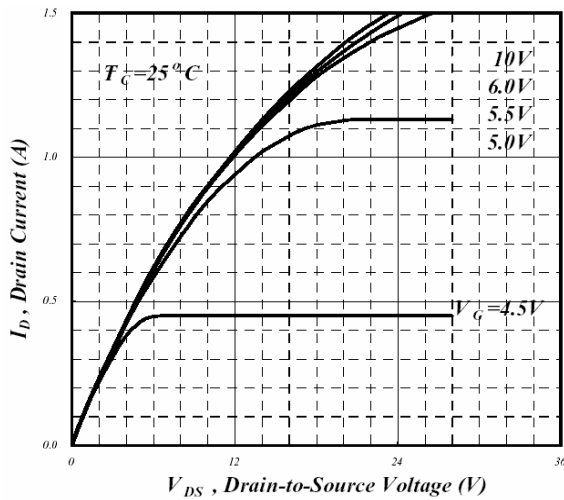
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward On Voltage <sup>3</sup>	V <sub>SD</sub>	-	-	1.2	V	I <sub>S</sub> =1A, V <sub>GS</sub> =0V, T <sub>j</sub> =25°C
Continuous Source Current (Body Diode)	I <sub>S</sub>	-	-	1	A	V <sub>D</sub> =V <sub>G</sub> =0V, V <sub>S</sub> =1.2V
Pulsed Source Current (Body Diode) <sup>1</sup>	I <sub>SM</sub>	-	-	5	A	

Notes: 1. Pulse width limited by safe operating area.

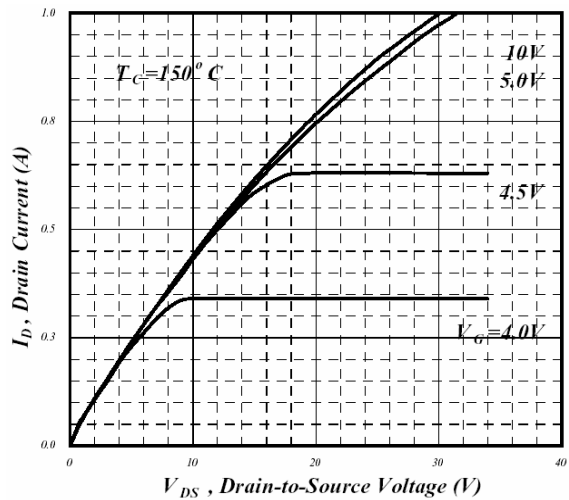
2. Staring T<sub>j</sub>=25°C, V<sub>DD</sub>=50V, L=1.0mH, R<sub>G</sub>=25Ω, I<sub>AS</sub>=1.0A.

3. Pulse width ≤ 300us, duty cycle ≤ 2%.

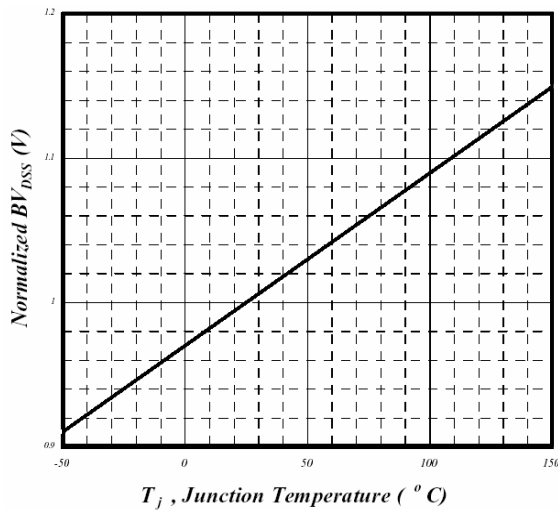
## Characteristics Curve



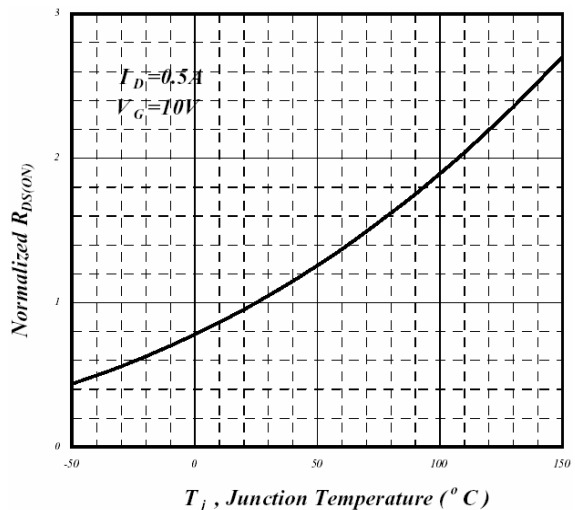
**Fig 1. Typical Output Characteristics**



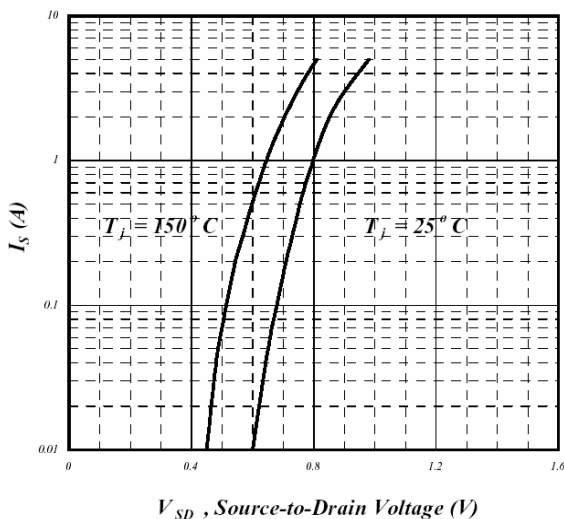
**Fig 2. Typical Output Characteristics**



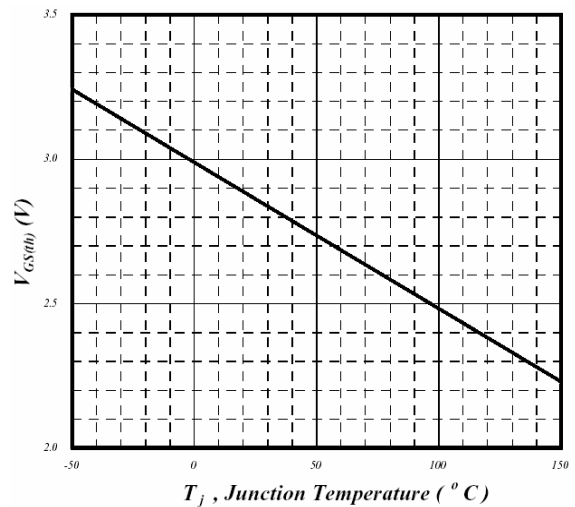
**Fig 3. Normalized BV<sub>DSS</sub> v.s. Junction Temperature**



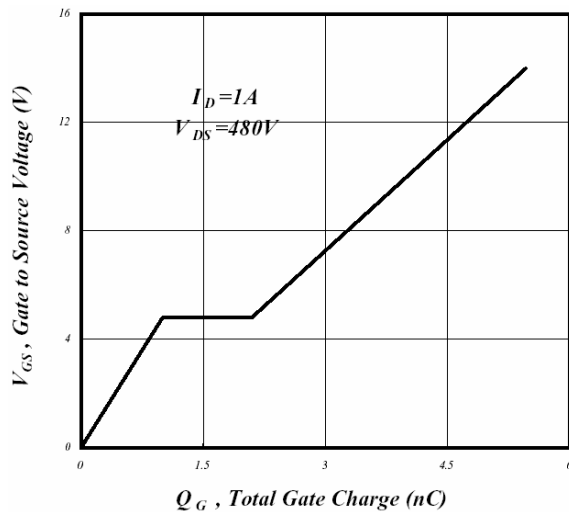
**Fig 4. Normalized On-Resistance v.s. Junction Temperature**



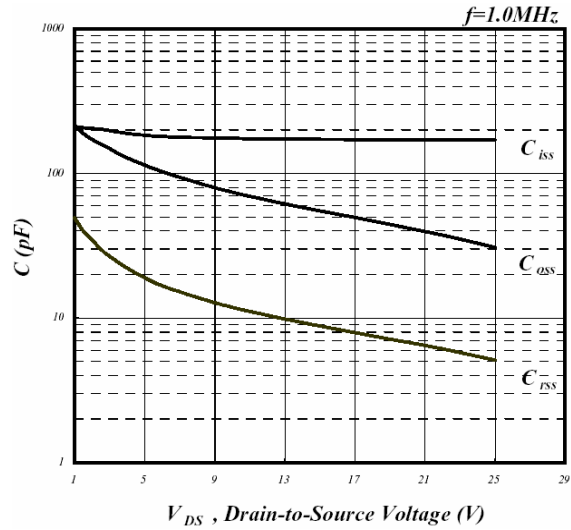
**Fig 5. Forward Characteristics of Reverse Diode**



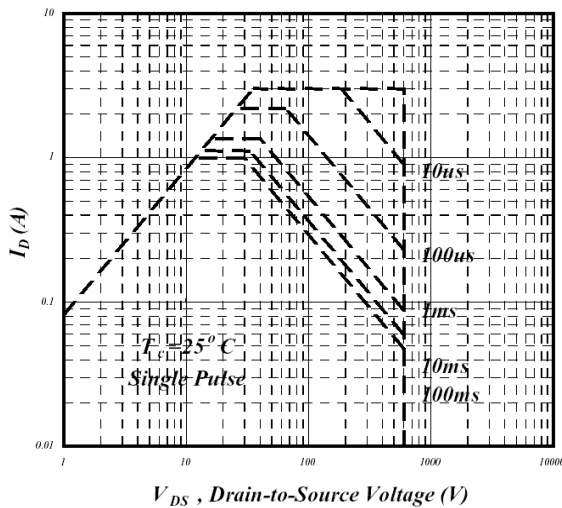
**Fig 6. Gate Threshold Voltage v.s. Junction Temperature**



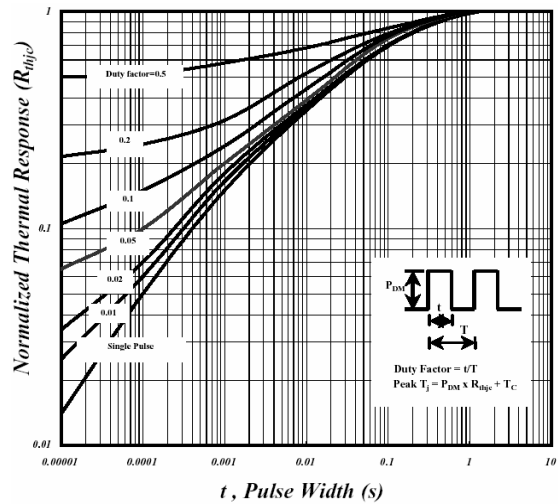
**Fig 7. Gate Charge Characteristics**



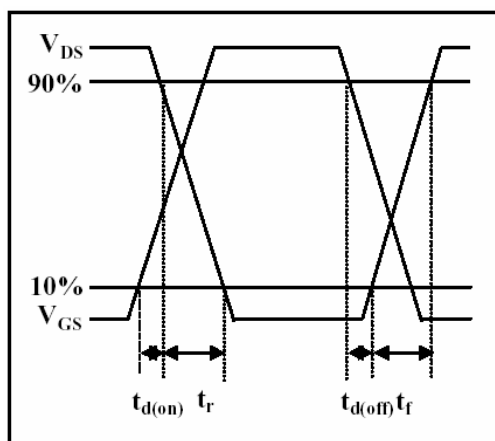
**Fig 8. Typical Capacitance Characteristics**



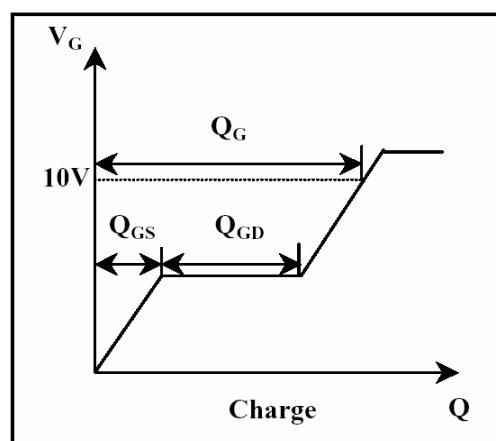
**Fig 9. Maximum Safe Operating Area**



**Fig 10. Effective Transient Thermal Impedance**



**Fig 11. Switching Time Waveform**



**Fig 12. Gate Charge Waveform**

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